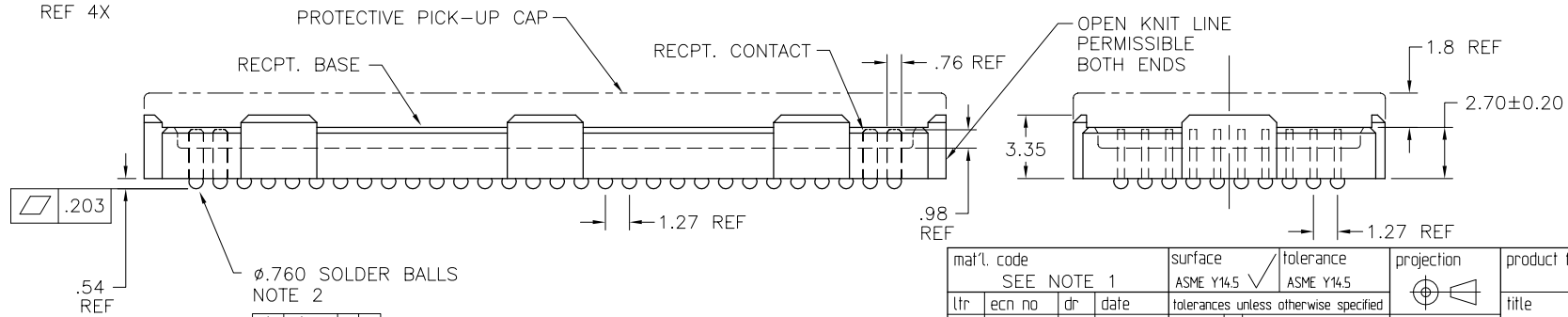
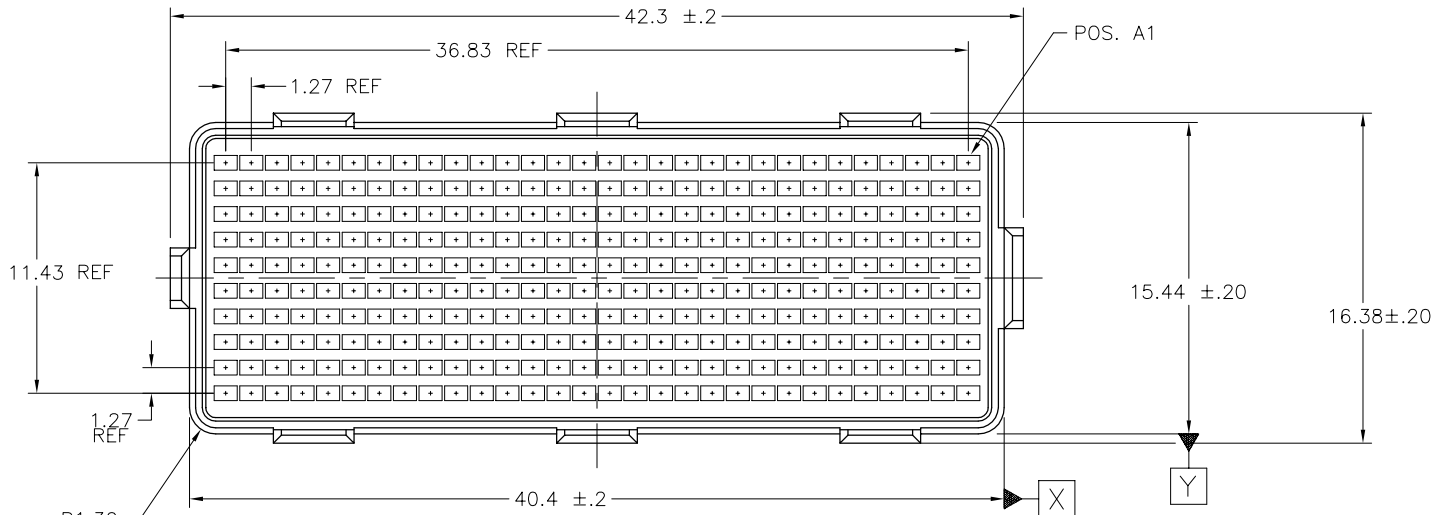
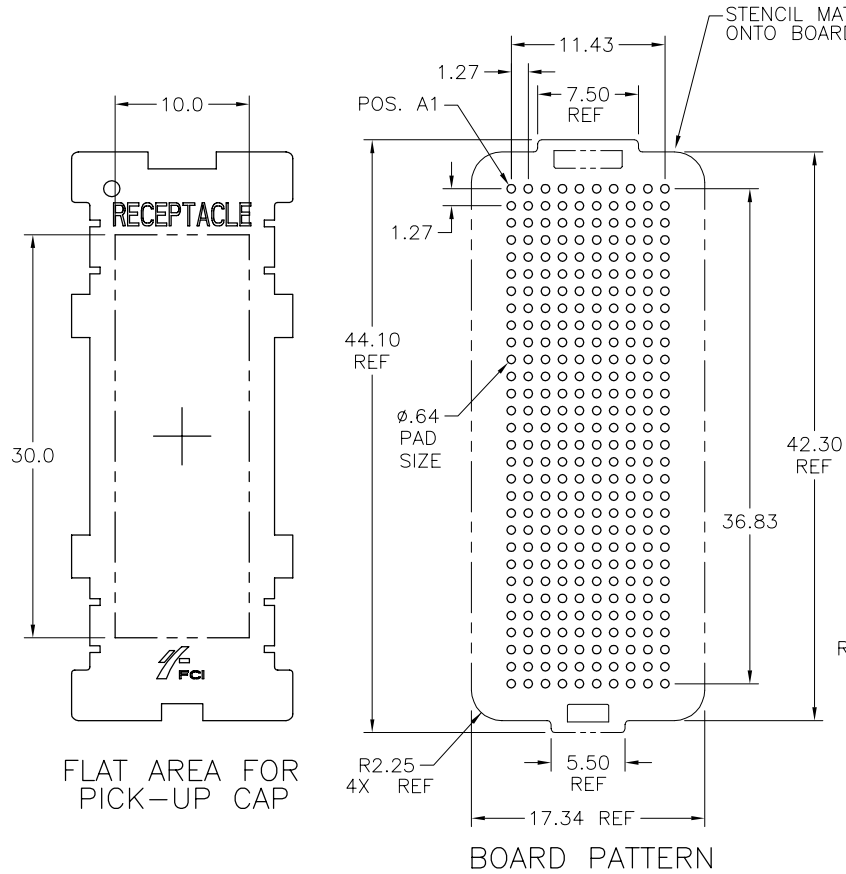


PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
84501-001	YES	15u" (.38um) Au OVER Ni	SnPb
84501-001LF			SnAgCu LEAD FREE (5)(6)
84501-101	YES	30u" (.76um) Au OVER Ni	SnPb
84501-101LF			SnAgCu LEAD FREE (5)(6)
84501-201	YES	SEE NOTE 4.	SnPb
84501-201LF			SnAgCu LEAD FREE (5)(6)

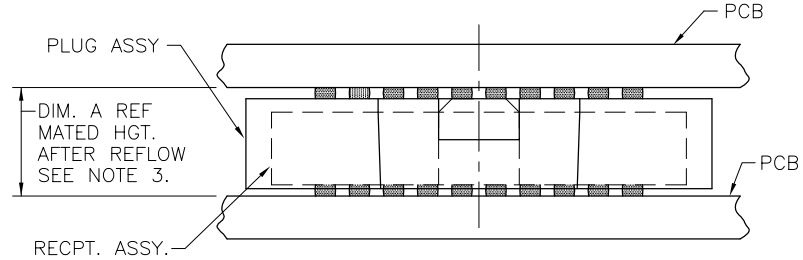


Ø.760 SOLDER BALLS  
NOTE 2  
⊕ Ø.30 | X | Y

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection ⊕		product family MEG-ARRAY	
ltr	ec'n no	dr	date	tolerances unless otherwise specified		MM		title 4mm RECP.T. ASSY. 10 X 30 = 300 POS.	
K	V06-0560	LP	2006/07/13	angles	X*3	→		sheet 1 of 3	
-	-	-	-	flat	XX*13	scale 3:1		size A4	
E	V20006	DRW	1/24/00	0° ±2'	XXX*051	FCI		dwg no 84501	
F	V20949	DAI	08/12/02	dr	D.WAUGHEN	12.18.98		type CUSTOMER Drawing	
G	V03-0680	DAI	06/19/03	engr	D.HARPER	12.18.98			
H	V04-0940	VS	10/18/04	chr	D.HARPER	12.18.98			
J	V05-1071	DAI	12/21/05	appd	D.HARPER	12.18.98			
sheet index	revision	K	K	K					
	sheet	1	2	3					



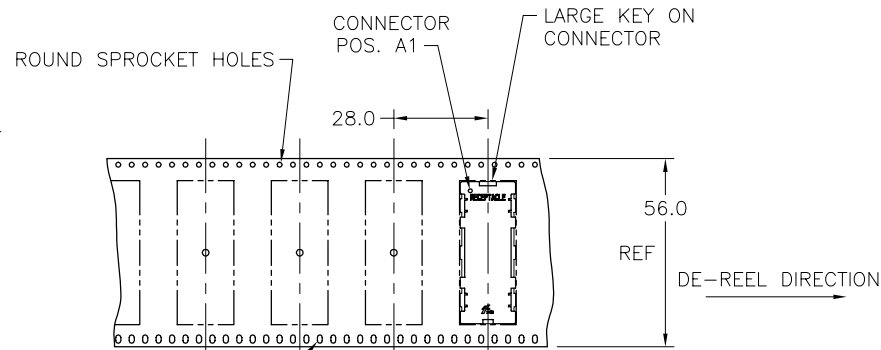
STENCIL MATED CONNECTOR OUTLINE ONTO BOARD.



MATED HEIGHT TABLE		
DIM. A	PLUG ASSY. P/N	RECPT. ASSY. P/N
4.0	84500	84501
10.0	84578	84501

MATED HEIGHT AFTER REFLOW IS BASED ON  $\phi$ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE



ELONGATED SPROCKET HOLES  
TAPES & REEL PACKAGING  
PER EIA 481-3  
SCALE NONE

mat'l. code SEE NOTE 1.		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified	title 4mm RECPT. ASSY. 10 X 30 = 300 POS.
k				angles X*.3 .XX*.13 0° ±2'	scale 2:1
		dr	D.WAUGHEN	12.16.98	dwg no 84501 sheet 2 of 3 size A4 type CUSTOMER Drawing
		enr	D.HARPER	12.16.98	
		chr	D.HARPER	12.16.98	
		appd	D.HARPER	12.16.98	
sheet index	revision sheet				

NOTES:

①. MAT'L

HOUSING: LCP  
CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1)  
SOLDER BALL: (SEE TABLE ON SHEET1)  
EUTECTIC SnPb OR LEAD FREE  
95.5Sn/4Ag/0.5Cu

②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④. PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).

⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

mat'l. code SEE NOTE 1.		surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY		
ltr	ecr no	dr	date	tolerances unless otherwise specified				title 4mm RECT. ASSY. 10 X 30 = 300 POS.		
k				angles	line fit	MM				
				0° ±2'		scale 2:1				
		dr	D.WAUGHEN	12.16.98				dwg no sheet 3 of 3 size		
		enr	D.HARPER	12.16.98	84501			A4		
		chr	D.HARPER	12.16.98						
		appd	D.HARPER	12.16.98			type CUSTOMER Drawing			
sheet index	revision sheet									